

PATENT Atty. Dkt. AMAT/3786.Y1/CMP/CMP/RKK

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Li, et al.

Serial No.: 09/469,709

Confirmation No.: 5296

Filed:

December 21, 1999

For:

High Through-Put CU CMP

With Significantly Reduced

Erosion

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

Group Art Unit: 1763

Examiner: George A. Goudreau

CERTIFICATE OF MAILING 37 CFR 1.8

I hereby certify that this correspondence is being deposited on 12/22, 2003 with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

13/22/12/23 B- 51 Signature

## SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

The Applicants, and the Attorney who signs below on the basis of the information supplied by the inventor and the information in his file, submit herewith patents, publications, or other information of which they are aware, which may be material to the examination of this application and in respect of which there may be a duty to disclose in accordance with 37 CFR § 1.56.

While the information submitted in this Supplemental Information Disclosure Statement may be material pursuant to 37 CFR § 1.56, it is not intended to constitute an admission that any patent, publication, or other information referred to therein is prior art for this invention unless specifically designated as such.

In accordance with 37 CFR § 1.97, this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or that no other possibly material information as defined under 37 CFR § 1.56(a) exists.

The patents and/or publications submitted herewith are set forth on the attached Form PTO-1449.

229889

Applicants certify that all references submitted with this disclosure were cited in a communication from a foreign patent office dated November 12, 2003, which communication is enclosed, not more than three months prior to the filing of this Supplemental Information Disclosure Statement.

The Commissioner is hereby authorized to charge sum of \$180.00 due under 37 CFR § 1.17(p) pursuant to § 1.97, and any other fee necessary to make this submission timely, to the Deposit Account No. 20-0872/AMAT/3786.Y1/BKH.

Respectfully submitted,

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Sheet 1 of 1 sheets U.S. Department of Commerce, Patent and Trademark Office Docket No. Serial No. (PTO Form 1449 modified) AMAT/3786.Y1/CMP/ 09/469,709 CMP/RKK SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT BY **Applicant** Confirmation No. 61PE **APPLICANT** Li, et al. 5296 (Use several sheets if necessary) Filing Date DEC 2 3 2003 Group George A. Goudrealu, Examiner December 21, 1999 1763 **U.S. Patent Documents** Applicant(s) \*Examiner Document Issue Class Subclass Filing Date If Initial Number Date Name **Appropriate A1** 6,001,730 12/14/1999 Farkas, et al. 438 627 10/20/1997 **A2** 5,994,224 11/30/1999 Sandhu, et al. 438 692 12/17/1997 **A3** 5.738.574 04/14/1998 Tolles, et al. 451 288 10/27/1995 **A4** 5,516,346 05/14/1996 Cadien, et al. 51 308 05/13/1994 **Foreign Patent Documents** \*Examiner Document Date Country Class Subclass Translation Initial Number YES NO X **B1** 1 085 067 11/31/1999 EP C09G 1/02 П **B2** 1 093 161 10/11/2000 EP H01L 21/768  $\boxtimes$ X **B3** 1 057 591 EP B24B 37/04 12/06/2000 X **B4** 00/35627 06/22/2000 WO B24B 冈 **B5** 98/49723 11/05/1998 WO H01L 21/321 **B6** 00/30154 05/24/2000 WO H01L 冈 **B7** 00/59031 10/05/2000 WO H01L Ø 21/768 **B8** 00/25984 05/11/2000 WO **B24B** 37/04  $\boxtimes$ **OTHER ART** \*Examiner Including Author, Title, Date, Pertinent Pages, Etc. Initial C1 European Search Report for 00311569.8 dated November 12, 2003 (AMAT/3786.EP) C2 Peterson, et al., "Investigating CMP and Post-CMP Cleaning Issues for Dual-Damascene Copper Technology" Micro Computerist, Volume 17 No. 1 January 1999 Pages 27-32, 34. C3 Hayashi, et al. "A New Two-Step Metal-CMP Technique for a High Performance Multilevel Interconnects Featured by Al-AND CU in Low Epsilon, Organic Film-Metallizations" 1996 Symposium on VLSI Technology, Digest of Technical Papers Pages 88-89. C4 Schraub, et al., "Chemical Mechanical Polishing: Future Processing Require CMP Tool Flexibility" Proceedings of the SPIE, Volume 3508 September 1998 Pages 146-154 Wijekoon, et al. "Development of a Production Worthy Copper CMP Process" Advanced C5 Semiconductor Manufacturing Conference and Workshop, September 1998, Pages 354-363. Examiner **Date Considered** \*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through

citation if not in conformance and not considered. Include copy of this form with your communication to applicant.